## **DISCRETE SEMICONDUCTORS**

# DATA SHEET

# **PDTA143X series** PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

Product specification Supersedes data of 2003 Apr 10 2004 Aug 04





### PDTA143X series

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

#### **APPLICATIONS**

- · General purpose switching and amplification
- · Inverter and interface circuits
- · Circuit driver.

### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	_	-50	V
Io	output current (DC)	_	-100	mA
R1	bias resistor	4.7	_	kΩ
R2	bias resistor	10	_	kΩ

#### **DESCRIPTION**

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TYPE NUMBER	PAC	KAGE	MARKING CODE	NPN COMPLEMENT
I TPE NUMBER	PHILIPS	EIAJ	MARKING CODE	NPN COMPLEMENT
PDTA143XE	SOT416	SC-75	35	PDTC143XE
PDTA143XEF	SOT490	SC-89	41	PDTC143XEF
PDTA143XK	SOT346	SC-59	25	PDTC143XK
PDTA143XM	SOT883	SC-101	DN	PDTC143XM
PDTA143XS	SOT54 (TO-92)	SC-43	TA143X	PDTC143XS
PDTA143XT	SOT23	_	*31 <sup>(1)</sup>	PDTC143XT
PDTA143XU	SOT323	SC-70	*46 <sup>(1)</sup>	PDTC143XU

#### Note

<sup>1. \* =</sup> p: Made in Hong Kong.

<sup>\* =</sup> t: Made in Malaysia.

<sup>\* =</sup> W: Made in China.

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

## PDTA143X series

### SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION
PDTA143XS	R1	1 2 3	base collector emitter
PDTA143XE PDTA143XEF PDTA143XK PDTA143XT PDTA143XU	3 1 R1 1 R2 1 DDB271	1 2 3	base emitter collector
PDTA143XM	2 R1 3 Bottom view MDB267	1 2 3	base emitter collector

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

### PDTA143X series

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-10	V
V <sub>I</sub>	input voltage				
	positive		_	+7	V
	negative		_	-20	V
Io	output current (DC)		_	-100	mA
I <sub>CM</sub>	peak collector current		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 µm copper strip line.

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

## PDTA143X series

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	_	_	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_{B} = 0$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_B = 0; T_j = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0$	_	_	-600	μΑ
h <sub>FE</sub>	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -10 \text{ mA}$	50	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	_	-150	mV
$V_{i(off)}$	input-off voltage	$I_C = -100 \mu\text{A};  V_{CE} = -5 \text{V}$	_	-0.9	-0.3	V
$V_{i(on)}$	input-on voltage	$I_C = -20 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-2.5	-1.5	_	V
R1	input resistor		3.3	4.7	6.1	kΩ
R2 R1	resistor ratio		1.7	2.1	2.6	
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = -10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	_	3	pF

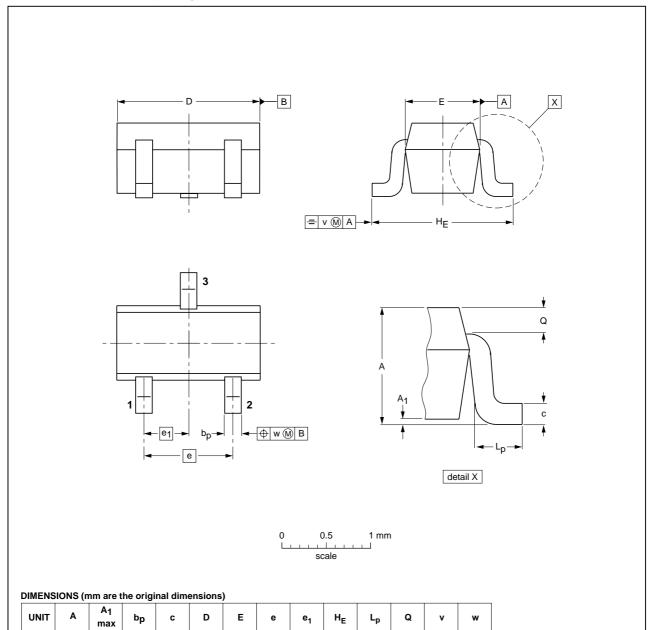
# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

## PDTA143X series

#### **PACKAGE OUTLINES**

### Plastic surface mounted package; 3 leads

**SOT416** 



OUTLINE VERSION		REFER	RENCES	EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT416			SC-75		97-02-28

1.75

1.45

1

0.5

0.45

0.23

0.2

0.2

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0.30

0.95

0.1

0.25

0.10

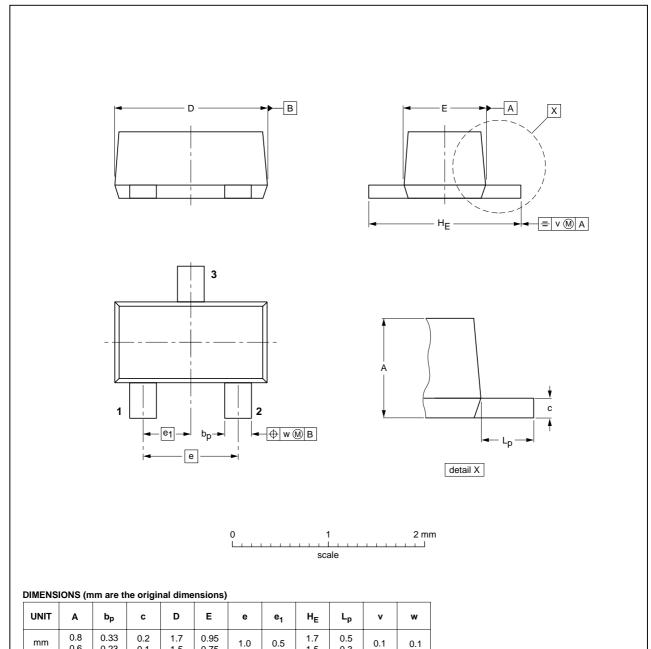
1.8

## PNP resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$ , $R2 = 10 \text{ k}\Omega$

## PDTA143X series

### Plastic surface mounted package; 3 leads

**SOT490** 



OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEDEC EIAJ I		PROJECTION	ISSUE DATE	
SOT490			SC-89		$\bigoplus \bigoplus$	98-10-23	

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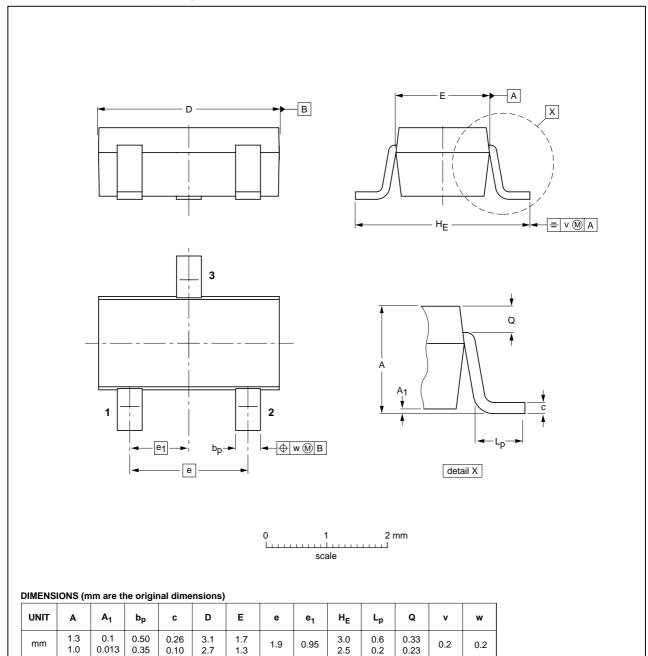
0.6

0.23

## PDTA143X series

### Plastic surface mounted package; 3 leads

**SOT346** 



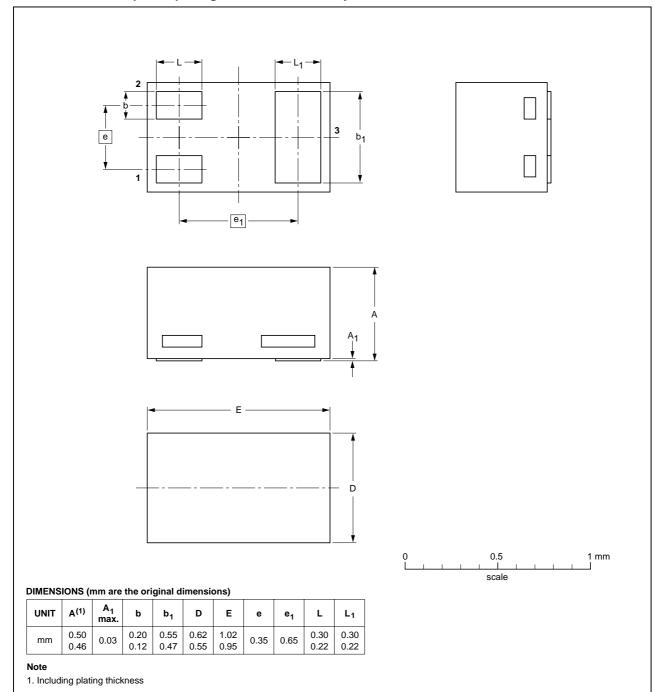
OUTLINE		REFER	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	
SOT346		TO-236	SC-59		98-07-17

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

## PDTA143X series

### Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



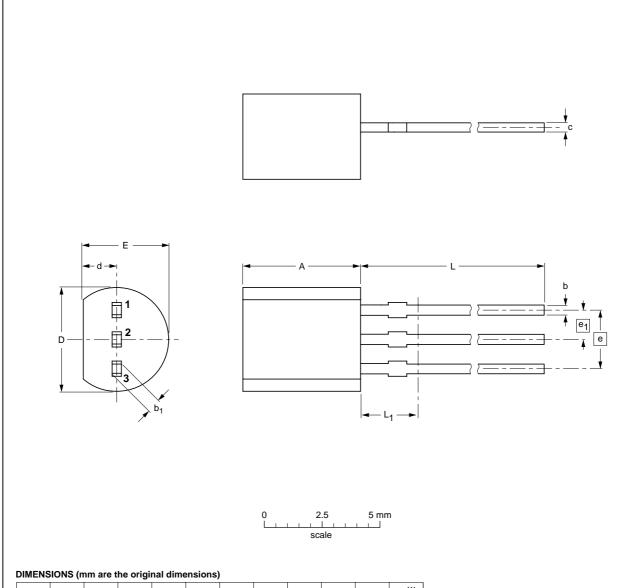
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT883			SC-101		<del>03-02-05</del> 03-04-03	

# PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

## PDTA143X series

### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

#### Note

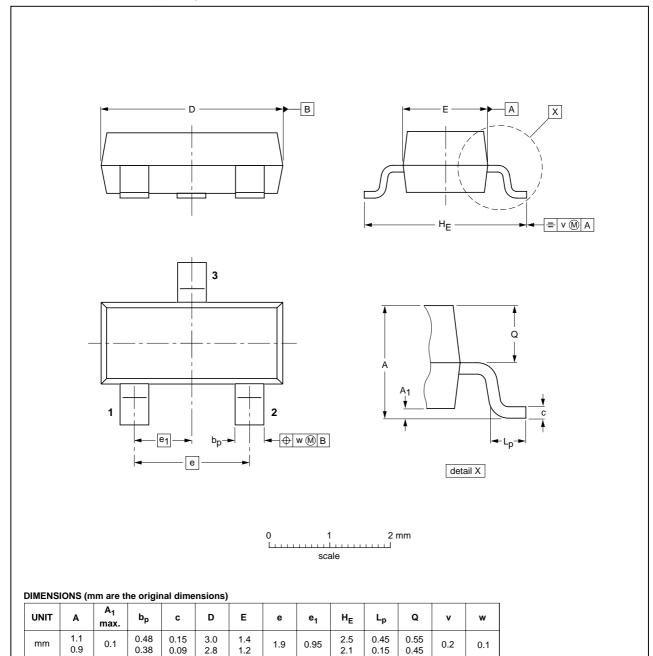
1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE		
VERSION	IEC JEDEC	JEDEC	JEITA	PROJECTION		ISSUE DATE	
SOT54		TO-92	SC-43A			<del>97-02-28</del> 04-06-28	

## PDTA143X series

### Plastic surface mounted package; 3 leads

SOT23

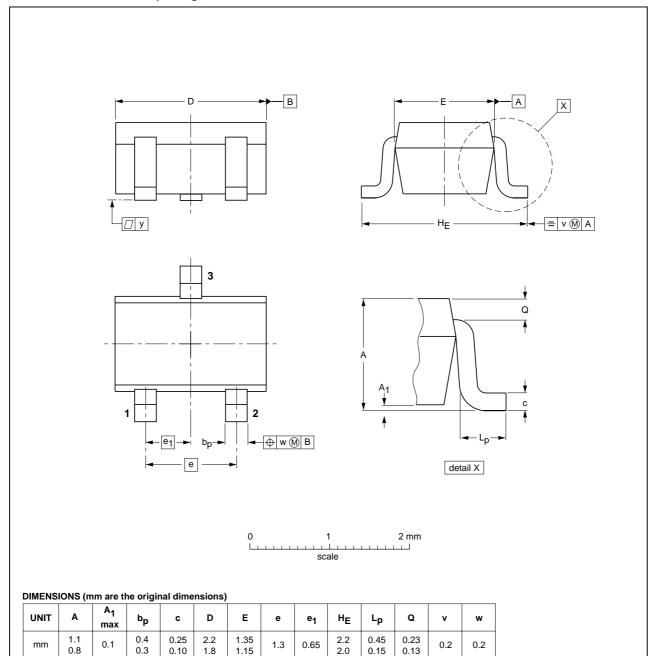


OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>-97-02-28</del> 99-09-13

## PDTA143X series

### Plastic surface mounted package; 3 leads

**SOT323** 



OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

## PNP resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 10 k $\Omega$

### PDTA143X series

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Printed in The Netherlands

R75/03/pp14

Date of release: 2004 Aug 04

Document order number: 9397 750 13657

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